SN74LS19A, SN74LS24A
SCHMITT-TRIGGER POSITIVE-NAND GATES
AND INVERTERS WITH TOTEM-POLE OUTPUTS

JANUARY 1981 — REVISED MARCH 1988

- Functionally and Mechanically Identical to 'LS13, 'LS14, and 'LS132, Respectively

- Improved Line-Receiving Characteristics

- P-N-P Inputs Reduce System Loading

- Excellent Noise Immunity with Typical Hysteresis of 0.8 V

SN74LS19A . . . D, J, OR N PACKAGE
(TOP VIEW)

```
       ___ ___
1A  [1  U  14] VCC
1Y  [2     13] 6A
2A  [3     12] 6Y
2Y  [4     11] 5A
3A  [5     10] 5Y
3Y  [6      9] 4A
GND [7      8] 4Y
```
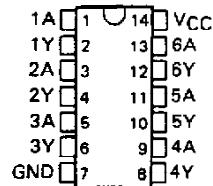
SN74LS24A . . . D, J, OR N PACKAGE
(TOP VIEW)

```
       ___ ___
1A  [1  U  14] VCC
1B  [2     13] 4B
1Y  [3     12] 4A
2A  [4     11] 4Y
2B  [5     10] 3B
2Y  [6      9] 3A
GND [7      8] 3Y
```

description

Each circuit functions as a NAND gate or inverter, but because of the Schmitt action, it has different input threshold levels for positive-going (V_{T+}) and for negative-going (V_{T-}) signals. The hysteresis or backlash, which is the difference between the two threshold levels ($V_{T+} - V_{T-}$), is typically 800 millivolts.

These circuits are temperature-compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals.

logic symbols[†]

SN74LS19A

SN74LS24A

logic diagrams (positive logic)

SN74LS19A

$Y = \overline{A}$

SN74LS24A

$Y = \overline{AB}$
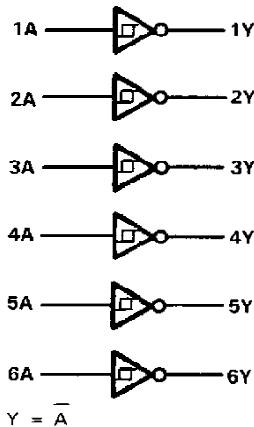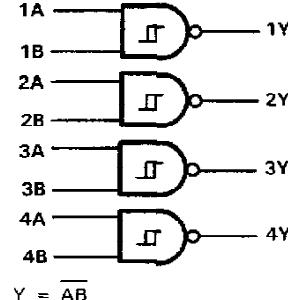
[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

TEXAS INSTRUMENTS

POST OFFICE BOX 655012 • DALLAS, TEXAS 75265

schematic (each gate)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage . . . . 7 V
Operating free-air temperature range . . . . 0°C to 70°C
Storage temperature range . . . . −65°C to 150°C

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
High-level output current, I_{OH}			−400	μA
Low-level output current, I_{OL}			8	mA
Operating free-air temperature, T_A	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			MIN	TYP‡	MAX	UNIT
V_{T+}	$V_{CC} = 5$ V			1.65	1.9	2.15	V
V_{T-}	$V_{CC} = 5$ V			0.75	1.0	1.25	V
Hysteresis $(V_{T+} - V_{T-})$	$V_{CC} = 5$ V			0.4	0.9		V
V_{IK}	$V_{CC} = $ MIN.	$I_I = -18$ mA				-1.5	V
V_{OH}	$V_{CC} = $ MIN,	$V_I = V_{T-min}$	$I_{OH} = -0.4$ mA	2.7	3.4		V
V_{OL}	$V_{CC} = $ MIN,	$V_I = V_{T+max}$	$I_{OL} = 4$ mA		0.25	0.4	V
			$I_{OL} = 8$ mA		0.35	0.5	
I_{T+}	$V_{CC} = 5$ V,	$V_I = V_{T+}$			-2	-20	μA
I_{T-}	$V_{CC} = 5$ V,	$V_I = V_{T-}$			-5	-30	μA
I_I	$V_{CC} = $ MAX,	$V_I = 7$ V				0.1	mA
I_{IH}	$V_{CC} = $ MAX,	$V_I = 2.7$ V				20	μA
I_{IL}	$V_{CC} = $ MAX,	$V_I = 0.4$ V				-50	μA
I_{OS}§	$V_{CC} = $ MAX,	$V_I = V_O = 0$ V		-20		-100	mA
I_{CCH}	$V_{CC} = $ MAX,	$V_I = 0$ V	'LS19A		9.9	18	mA
			'LS24A		6.6	12	
I_{CCL}	$V_{CC} = $ MAX,	$V_I = 4.5$ V	'LS19A		17	30	mA
			'LS24A		11	20	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25°C$.
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

**switching characteristics, $V_{CC} = 5$ V, $T_A = 25°C$ (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	SN74LS19A			SN74LS24A			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	Any	Y	$R_L = 2$ kΩ, $C_L = 15$ pF		13	20		13	20	ns
t_{PHL}	Any	Y			18	30		25	40	ns

t_{PLH} = Propagation delay time, low-to-high-level output
t_{PHL} = Propagation delay time, high-to-low-level output

PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT

VOLTAGE WAVEFORMS
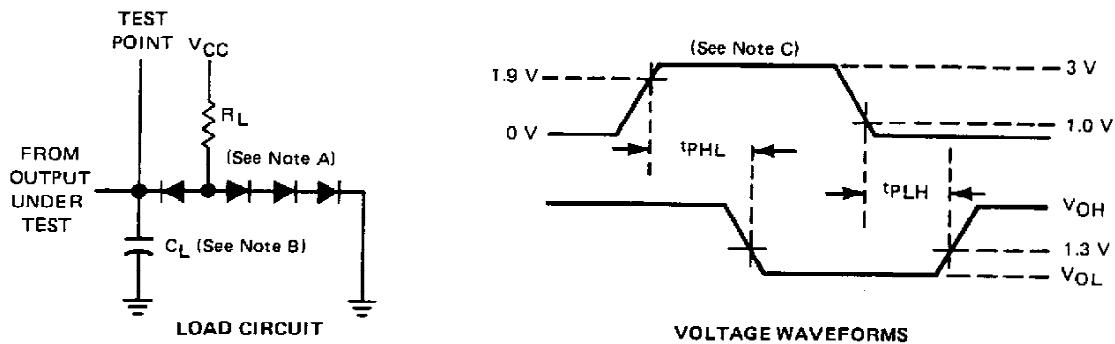
NOTES: A. All diodes are IN3064 or equivalent.
B. C_L includes probe and circuit capacitance.
C. The generator characteristics are: PRR = 1 MHz, t_r = 15 ns, t_p = 6 ns, Z_o = 50 Ω.

FIGURE 1

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LS19ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS19ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS19ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS19AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS19ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS19ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS19ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS19ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS24AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS24AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS
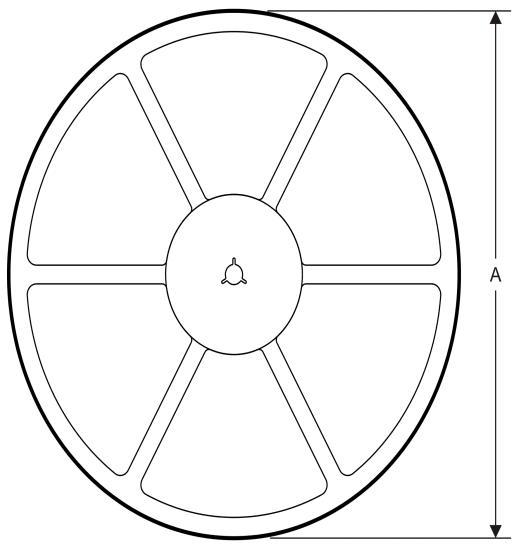
TAPE DIMENSIONS
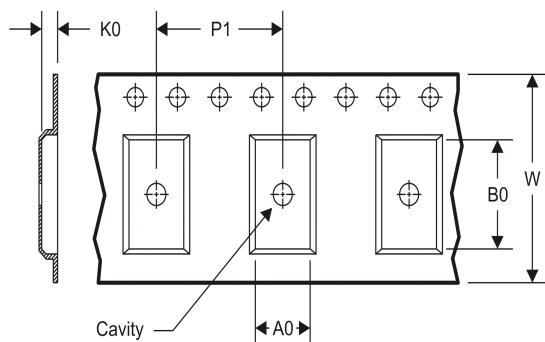
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers
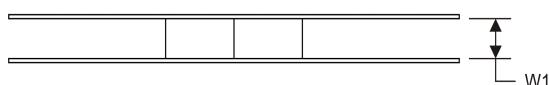
TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS19ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS19ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS
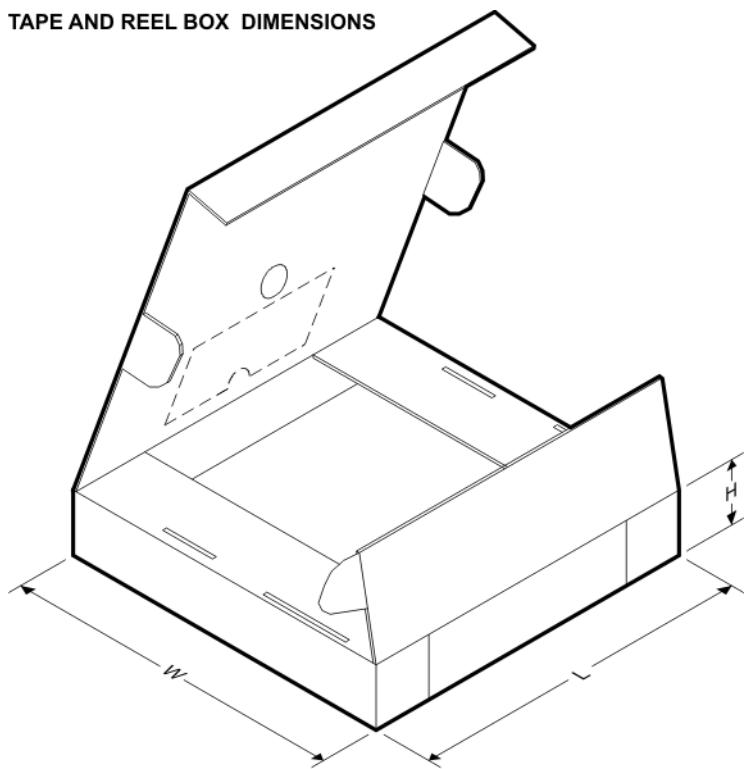
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS19ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS19ANSR	SO	NS	14	2000	367.0	367.0	38.0

N (R−PDIP−T**)   PLASTIC DUAL−IN−LINE PACKAGE
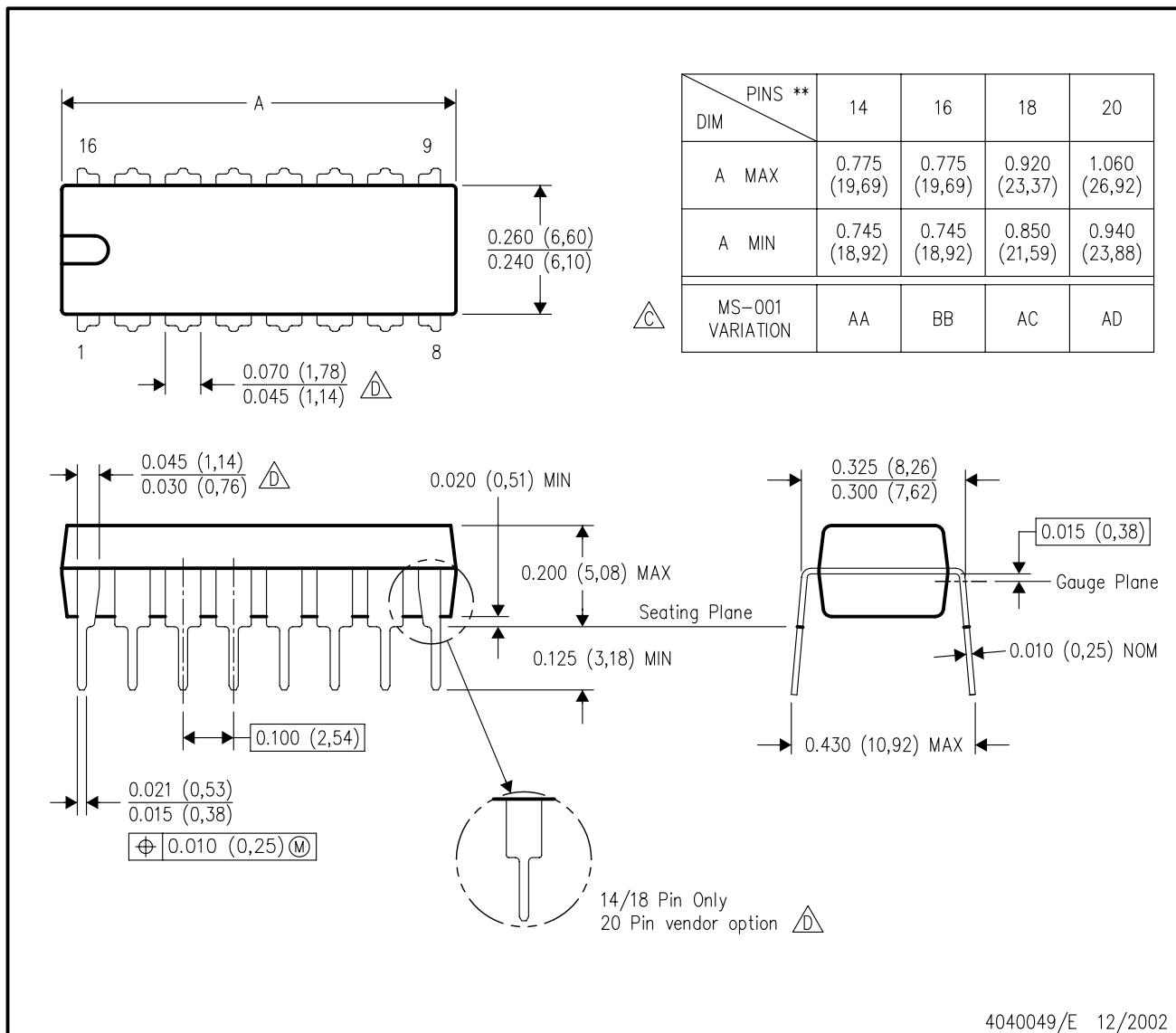
16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION △C	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) △D

0.045 (1,14) / 0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
       △C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
       △D The 20 pin end lead shoulder width is a vendor option, either half or full width.
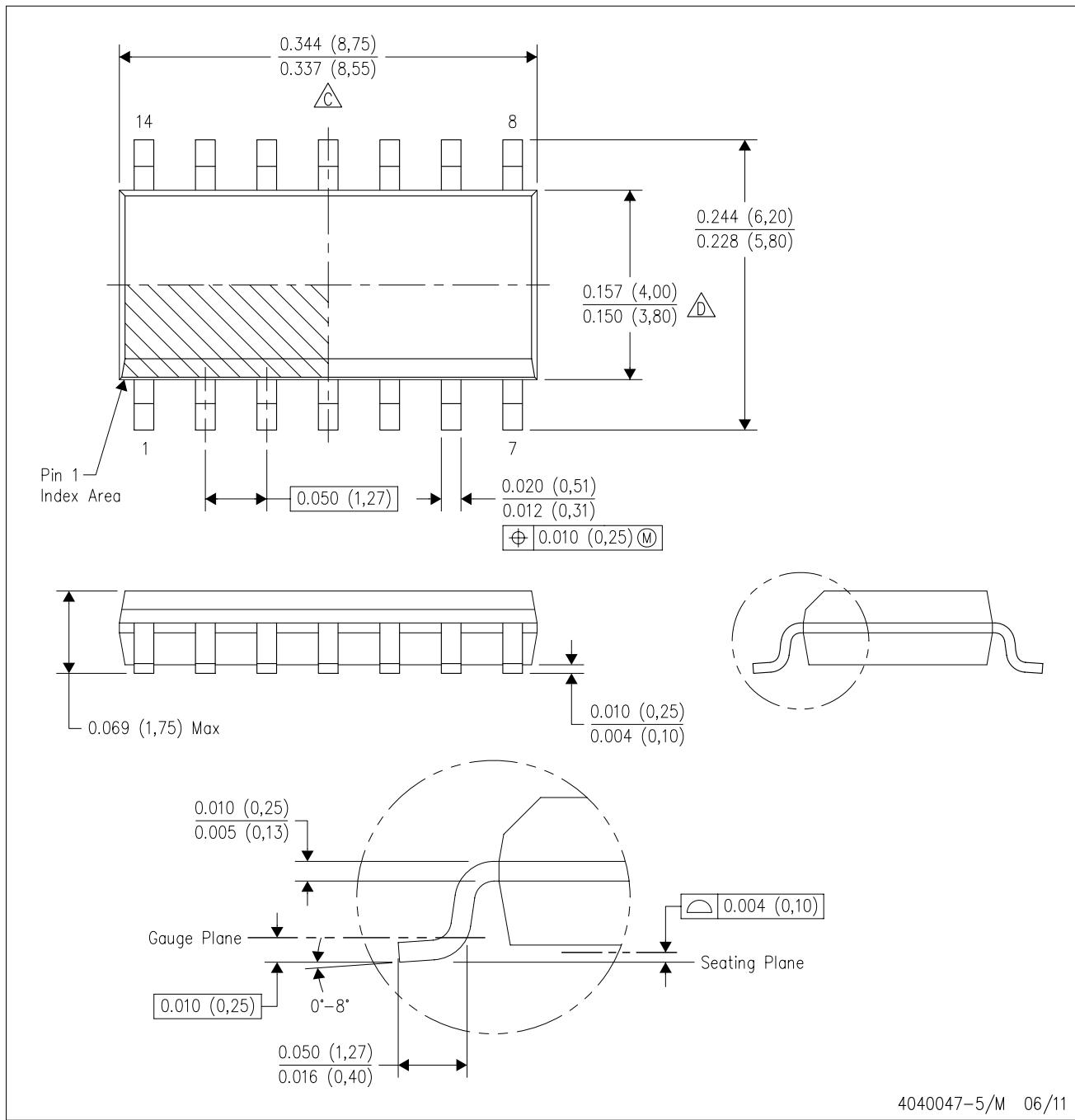
D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
⟨C⟩

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⟨D⟩

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
         ⟨C⟩ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
         ⟨D⟩ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E. Reference JEDEC MS−012 variation AB.

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D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40
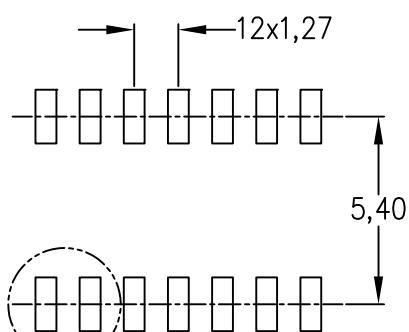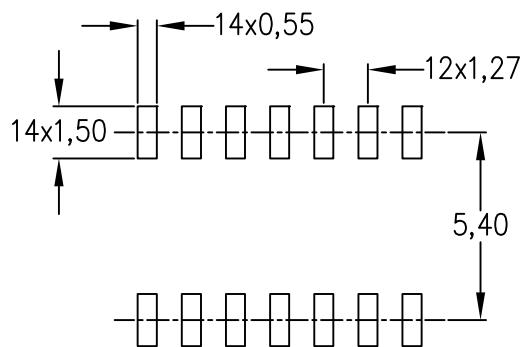
Example
Non Soldermask Defined Pad
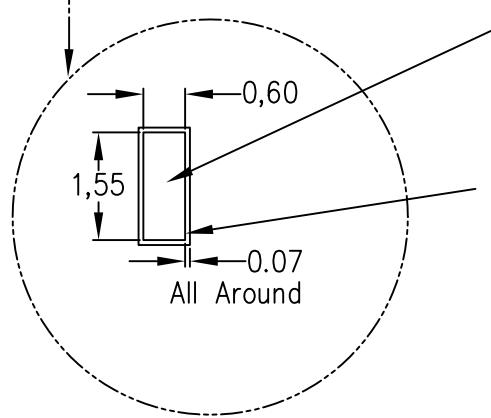
Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0.07
All Around

4211283−3/E 08/12

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Publication IPC−7351 is recommended for alternate designs.
          D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
               contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70
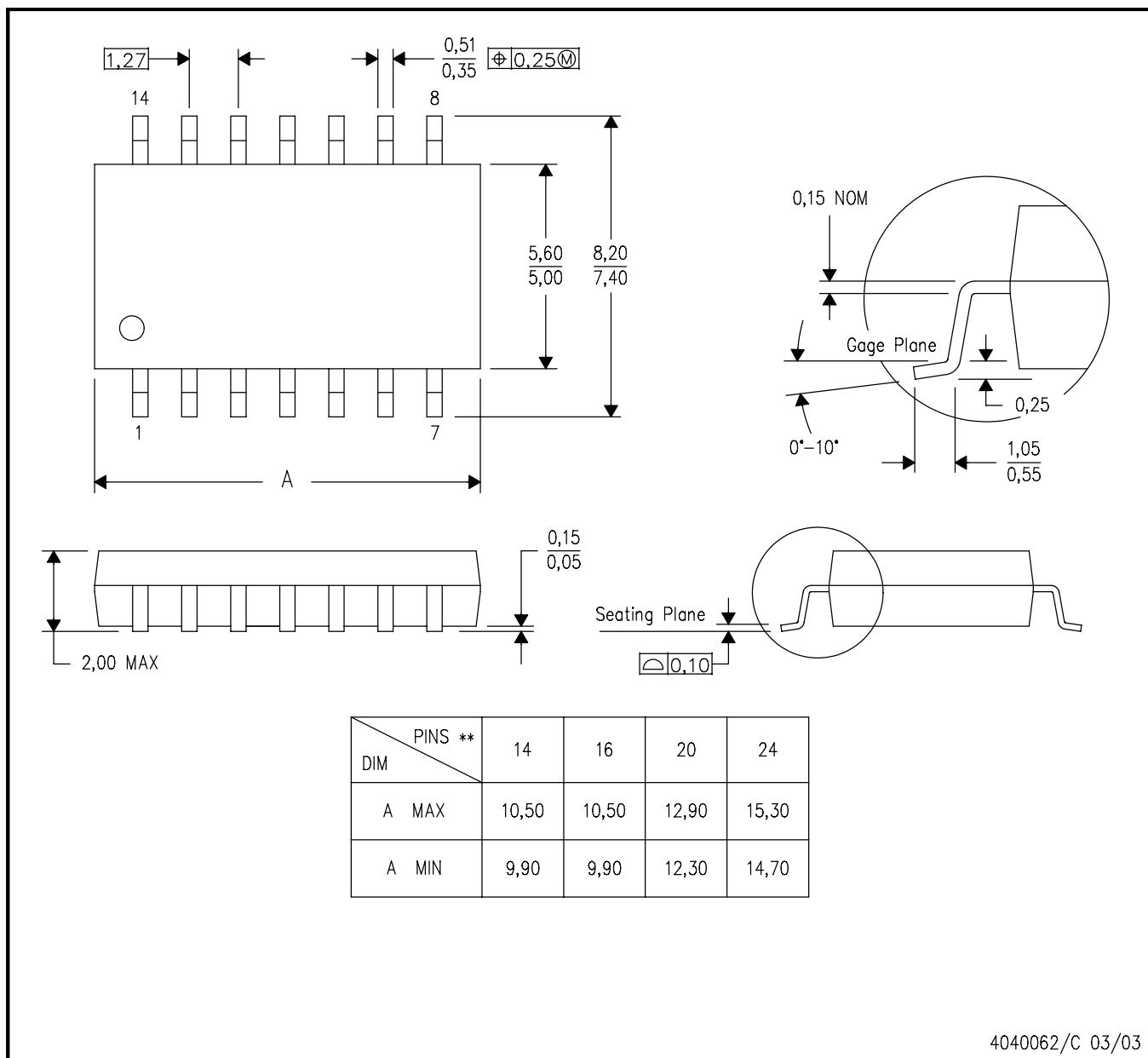
4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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